IEEE THE INSTITUTE OF ELECTRICAL AND ELECTRONICS ENGINEERS, INC. IEEE ELECTRONICS PACKAGING SOCIETY

# IEEE Electronics Packaging Society (EPS) - Phoenix Chapter

**Formerly Known as Components, Packaging and Manufacturing Technology (CPMT) Society**

**Wednesday, September 27, 2017: 5:30 PM**

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## Advancements in High Density Fan-out and Heterogeneous Integration


**Curtis Zwenger**

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**ABSTRACT**

An advanced high-density fan-out structure called Silicon Wafer Integrated Fan-out Technology (SWIFT®) incorporates conventional WLFO processes with leading-edge thin film patterning techniques to bridge the gap between TSV and traditional WLFO packages. The SWIFT methodology is designed to provide increased I/O and circuit density within a reduced footprint and profile for single and multi-die applications. The unique characteristics of the SWIFT process enable the creation of innovative structures that address the need for IC integration in emerging mobile and networking applications. This presentation will review the development of the SWIFT technology and its extension into high performance 2D and 3D structures. In addition, the advantages of SWIFT designs will be reviewed in comparison to current competing packaging technologies and to illustrate how the SWIFT is poised to provide robust, reliable, and low-cost packaging solutions for advanced mobile and networking products.


SWIFT is a registered trademark of Amkor Technology, Inc.

**BIOGRAPHY**

**Curtis Zwenger, VP**
**Adv. Package & Technology Integration**
**Amkor Technology**

Curtis joined Amkor in 1999 and has held leadership roles in developing Amkor's Fine Pitch Copper Pillar, Through Mold Via, and MEMS packaging technologies. He is currently responsible for the development and commercialization of Amkor's Advanced Wafer Level Fan-Out package technologies, including WLFO and SWIFT®. Prior to joining Amkor, Curtis worked for Motorola. He holds a degree in mechanical engineering from Colorado State University and an MBA from the University of Phoenix.

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**Date:** Wednesday, September 27, 2017, 5:30 PM

**Location:**

**Meeting Room A**
**Tempe Public Library**
**3500 S. Rural Road, Tempe, AZ 85282**
**(S-W corner of Rural & Southern Ave.)**
https://www.google.com/maps/dir/''/tempe+library/

**Agenda:** 5:30–6:00 PM: Networking & Refreshments,
6:00–7:00 PM: Presentation,
7:00 – 7:30 PM Questions & Answers

(Snacks and Soda will be provided by the IEEE Phoenix Section, Electronics Packaging Society)
IEEE members and non-members are all welcome to attend. The presentation promptly starts at 6:00 PM.

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***For more information, please contact any of the following EPS officers:***


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